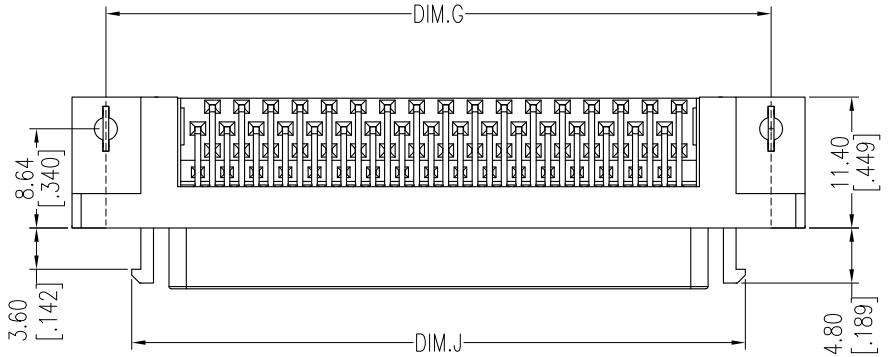
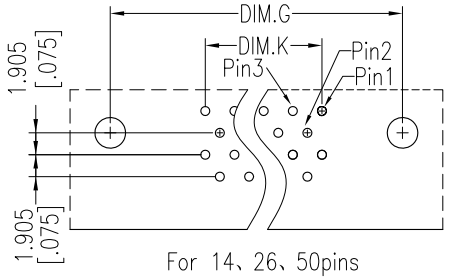
# HSF

NOTES:
Current Rating: 3.0AMP
Contact Resistance: 35mΩ Max
Withstand Voltage: 500V AC/DC
Insulation Resistance: 500MΩ Min
Operation Temperature: −40℃ to +105℃

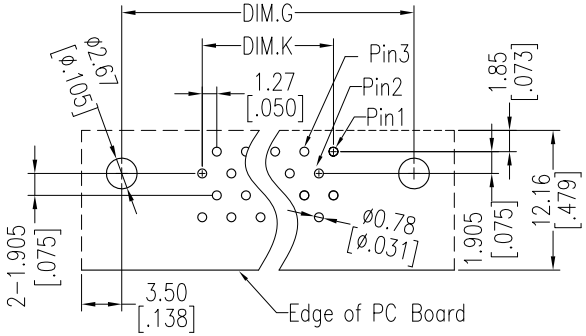
Contact Material:Phosphor Bronze
Contact Plating:Au and Sn over Ni
Shell Material:Zinc Alloy
Shell Plating:Ni 100u"
Fixing Material:Phosphor Bronze
Flxing Plating:Sn over Ni
Housing Material:PBT+30%G.F(UL94V−0)
Cover Material:PBT+30%G.F(UL94V−0)



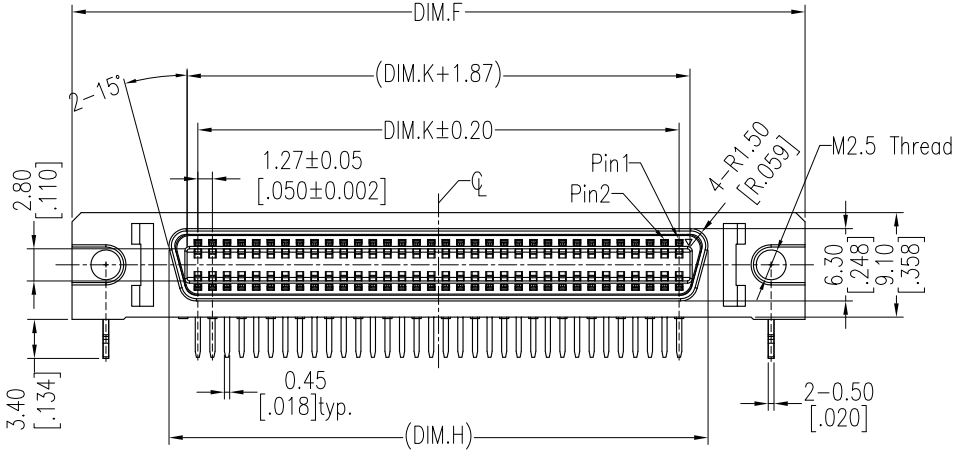

Recommended P.C.B Layout(Top Side)
(PCB BOARD TOLERANCE±0.05)

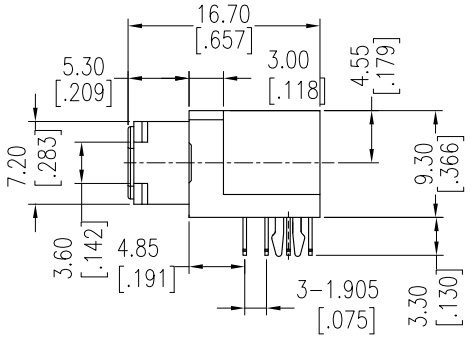



For 14、26、50pins




For 20、36、68pins




## *Ordering Information*

6321-0 XX R D SX M W A 01

| No.of Pins | Contact Plating | |
|---|---|---|
| 14P 36P<br>20P 50P<br>26P 68P | S1=3u"Gold/Tin<br>S3=10u"Gold/Tin<br>S4=15u"Gold/Tin<br>S5=30u"Gold/Tin | A=Tray |

A1

| | | | | | |
|---|---|---|---|---|---|
| 53.43 | 41.91 | 46.83 | 57.93 | 63.83 | 68 |
| 42.00 | 30.48 | 35.40 | 46.50 | 52.40 | 50 |
| 33.11 | 21.59 | 26.51 | 37.61 | 43.51 | 36 |
| 26.76 | 15.24 | 20.16 | 31.26 | 37.16 | 26 |
| 22.95 | 11.43 | 16.35 | 27.45 | 33.35 | 20 |
| 19.14 | 7.62 | 12.54 | 23.64 | 29.54 | 14 |
| DIM.J | DIM.K | DIM.H | DIM.G | DIM.F | PIN数 |

| REV | DATE | MODIFICATION DESCRIPTION | CHANGE |
|---|---|---|---|
| A1 | 2013/08/28 | Modify DIM.H | ------ |
| A0 | 2013/07/03 | NEW | ------ |

| OPERATION | | DRAW | DATE |
|---|---|---|---|
| X.X | ±0.40 | JYHuang | 2013/08/28 |
| X.XX | ±0.25 | CHECK | DATE |
| X.XXX | ±0.15 | | |
| Angle | ± 3° | APPROVE | DATE |
| DIM | TOL | | |

| SCALE | FIT |
|---|---|
| UNIT | mm |
| SIZE | A4 |
| SHEET | 1/2 |
| PROJ. | |

PART NO.
6321-0XXRDSXMWA01

TITLE:
1.27PITCH CEN TYPE
SCSI FEMALE DIP(鱼叉纵向)

Customer NO.